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PATENT APPLICATION

NTHE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Attn: OIPE

Masakazu SATO et al.

Application No.:

10/517,655

Docket No.:

122035

Filed: December 13, 2004

For:

METHOD OF EVALUATING SHAPE OF SEMICONDUCTOR WAFER AND

APPARATUS FOR EVALUATING SHAPE OF SEMICONDUCTOR WAFER

REQUEST FOR CORRECTION OF PALM RECORDS

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records.

Respectfully submitted,

William P. Berridge Registration No. 30,024

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WPB:JOC/emt

Date: July 29, 2005

OLIFF & BERRIDGE, PLC P.O. Box 19928 Alexandria, Virginia 22320 Telephone: (703) 836-6400 DEPOSIT ACCOUNT USE AUTHORIZATION Please grant any extension necessary for entry; Charge any fee due to our Deposit Account No. 15-0461



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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY.DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/517,655	12/13/2004	281,2	6600	122035	8	132	2

CONFIRMATION NO. 7281

25944 **OLIFF & BERRIDGE, PLC** P.O. BOX 19928 ALEXANDRIA, VA 22320

FILING RECEIPT *OC000000016250423*

Date Mailed: 06/13/2005

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Applicant(s)

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Assignment For Published Patent Application

SHIN-ETSU HANDOTAI CO LTD, Chiyoda-ku, JAPAN

Power of Attorney: The patent practitioners associated with Customer Number 25944.

Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP03/07320 06/10/2003

Foreign Applications

JAPAN 2002173268 06/11/2002

Projected Publication Date: 09/22/2005

Non-Publication Request: No

Early Publication Request: No

Title

-Semiconductor wafer shape evaluating method and shape evaluating device.

Method of Evaluating Shape of Semiconductor water and Preliminary Class

Apparatus for Evaluating Shape of Semiconductor Water

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